

Features

- For Use With:
Universal
Rectangular Alu
- Mounting: Adhesive
Foil
- Thermal Resistance
26.5°C/W

RS PRO Heatsinks

RS Stock No.: 7500881



RS PRO Professionally Approved Products bring to you professional quality parts across all product categories. Our product range has been tested by engineers and provides a comparable quality to the leading brands without paying a premium price.

Product Description

Push pin type BGA heatsink suitable for surface mount chip cooling and various other applications.

General Specifications

For Use With	Universal Rectangular Alu
Material	Aluminium
Mounting	Adhesive Foil
Application	High Power Semiconductor Device, Optoelectronic Device
Finish	Anodized
Notes	<ul style="list-style-type: none">• Thermal Resistance is calculated based on a distributed heat load and vertically mounted fins anodised heatsink with a 60°C temperature.• Under general operating conditions the thermal mounting arrangement of the device is not know and therefore the figures should be used as a guide to selection.• We recommend that the effectiveness of any heatsink is tested in the specific operating environment in which it will be subjected.

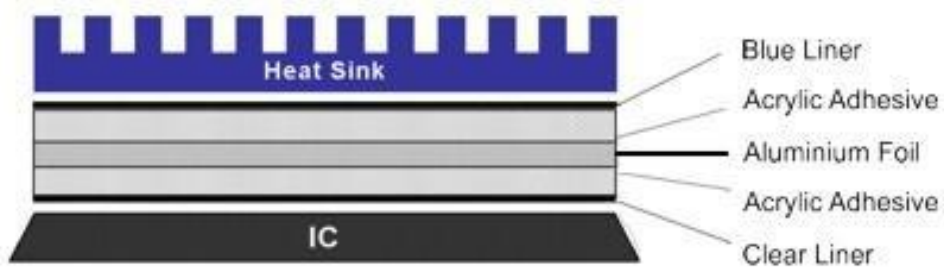
Mechanical Specifications

Length	14mm
Width	14mm
Height	10mm
Dimension	14 x 14 x 10mm

Electrical Specifications

Thermal Resistance	26.5°C/W
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Drawing below is for illustration purposes only. If any further information is required please contact us.



Colour	-	White
Backing Type / Thickness	Mm	Aluminium Foil / 0.10
Adhesive Type / Thickness	Mm	Arylic 0.075 (on clear liner side)
Total Thickness	mm	0,27
Adhesion	Kg/25mm	1,5
Thermal Conductivity	W/m-K	0,95
Thermal Resistance	°C-in ² /W	0,2
Holding Power@23°C	Hour	>72
Holding Power @ 130°C	Hour	>2